DEMO MANUAL DC252 DESIGN-READY SWITCHER

TECHNOLOGY LTC1736 5-Bit VID Constant Frequency Synchronous DC/DC Converter

DESCRIPTION

Demonstration Circuit DC252 is designed for mobile 5-bit VID-programmed notebook CPU applications using the LTC®1736 switching regulator controller. A high performance, constant frequency current mode architecture generates a precise low voltage CPU core supply. Protection features include an externally defeatable overcurrent latchoff and internal current foldback for overload conditions. A soft-latched crowbar monitors the output voltage for overvoltage protection. OPTI-LOOP™ compensation allows the transient response to be optimized over a wide range of output capacitance and ESR values. The circuit was designed for a 5V to 24V input range but allows a 4.5V to 28V range (limited by the external MOSFETs). Strong output drivers easily handle large power MOSFETs effi-

ciently. Output voltages can be configured according to Intel mobile VID standards of 0.9V to 2.0V. An internal power-good circuit monitors the output voltage for out-of-regulation conditions. External frequency synchronization is provided, as are three modes of operation: Burst Mode™ operation to reduce switching losses and maintain high operating efficiencies, burst inhibit/forced continuous mode and a low noise pulse-skipping mode that provides constant frequency operation down to 1% maximum load currents with low quiescent current. This results in a power supply that has very high efficiency, low ripple and fast transient response. **Gerber files for this circuit board are available. Call the LTC factory.**

(T), LTC and LT are registered trademarks of Linear Technology Corporation.

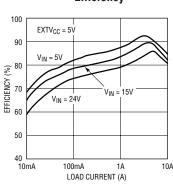
Burst Mode and OPTI-LOOP are trademarks of Linear Technology Corporation.

PERFORMANCE SUMMARY

PARAMETER	CONDITIONS	VALUE	
Input Voltage Range	put Voltage Range (Maximum Input Voltage Limited By External MOSFET and Input Capacitor)		
Output	Output Voltage (Programmed with a 5-Bit Mobile VID Code)	0.9V to 2.0V	
	Max Output Current (Continuous)	11.0A	
	Max Output Current (Peak)	12A	
	Typical Output Ripple Measured with 10MHz Bandwidth (Burst Mode Operation) I ₀ = 100mA	45mV _{P-P}	
	Typical Output Ripple Measured with 10MHz Bandwidth (Continuous) I ₀ = 5A	20mV _{P-P}	
V_{IN}	Line Regulation 5V to 24V	0.002%/V	

TYPICAL PERFORMANCE CHARACTERISTICS AND BOARD PHOTOS

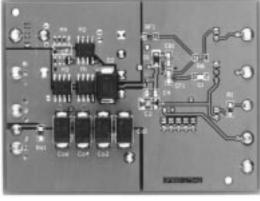
Efficiency



Component Side



Solder Side





PERFORMANCE SUMMARY

PARAMETER	CONDITIONS	VALUE
I _{OUT}	Load Regulation: No Load to Full Rated Output	-0.3%
I_Q	Supply Current (Typical), No Load, V _{IN} = 15V, FCB = INTV _{CC}	
	Supply Current in Shutdown (Typical), V _{IN} = 15V	15μΑ
I _{EXTVCC}	EXTV _{CC} Pin Current, V _{EXTVCC} = 5V, V _{IN} = 10V, FCB = INTV _{CC} , No Load, V _{OUT} = 1.6V	850μΑ
$\overline{V_{RUN}}$	Run Pin Threshold (Typical)	1.3V
Frequency	Operating Frequency (Typical), C _{OSC} = 47pF	270kHz

PACKAGE AND SCHEMATIC DIAGRAM

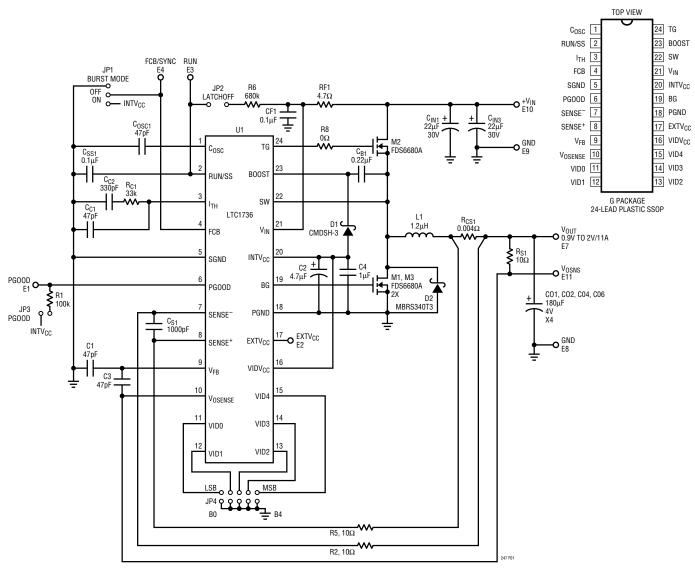


Figure 1. Demo Board Schematic

LTC1736CG24

PARTS LIST

REFERENCE	QUANTITY	PART NUMBER	DESCRIPTION	VENDOR	TELEPHONE
C1, C3	2	08055A470JAT1A	47pF 50V 5% NPO Capacitor	AVX	(843) 946-0362
C2	1	TACR475M010R	4.7μF 10V 20% Tantalum Capacitor	AVX	(207) 282-5111
C4	1	0805ZC105MAT1A	1μF 10V 20% X7R Capacitor	AVX	(843) 946-0362
CC1	1	08055A470JAT1A	47pF 50V 5% NPO Capacitor	AVX	(843) 946-0362
CC2	1	08055A331MAT1A	330pF 50V 5% NPO Capacitor	AVX	(843) 946-0362
CB1	1	08055A224KAT1A	0.22µF 50V 20% X7R Capacitor	AVX	(843) 946-0362
CF1, CSS1	2	08055A104MAT1A	0.1µF 50V 20% X7R Capacitor	AVX	(843) 946-0362
CIN1, CIN3	2	30SC22M	22μF 30V OS-CON Capacitor	SANYO	(619) 661-6835
CIN1, CIN3	0PT	THCR70E1H2262T	22μF 50V 20% Y5U Capacitor	MARCON	(847) 696-2000
C01, C02, C04, C06	4	EEFUE0G181R	180μF 4V SP Capacitor	PANASONIC	(201) 348-7522
C01, C02, C04	0PT	T510X447M006AS	470μF 6.3V Low ESR Tantalum Capacitor	KEMET	(408) 986-0424
C03, C05	0PT	4SP820M	820µF 4V OS-CON Capacitor	SANYO	(619) 661-6835
C _{OSC1}	1	08055A470JAT1A	47pF 50V 5% NPO Capacitor	AVX	(843) 946-0362
CS1	1	08055A102MAT1A	1000pF 50V 5% NPO Capacitor	AVX	(843) 946-0362
D1	1	CMDSH-3	BVR = 30V, 0.1A Schottky Diode	CENTRAL	(516) 435-1110
D2	1	MBRS340T3	BVR = 40V, 3A Schottky Diode	ON SEMICONDUCTOR	(800) 282-9855
E1, GND, +V _{IN} , V _{OSNS} , V _{OUT1}	5	1593-2	Turret Terminal (Small)	KEYSTONE	(718) 956-8900
E2, E3, E4, E8, E9, GND, +V _{IN} , +V _{OUT}	8	1502-2	Turret Terminal	KEYSTONE	(718) 956-8900
JP1	1	2802S-03-G2	2mm 3-Pin Header	COMM CON	(626) 301-4200
JP2, JP3	2	2802S-02-G2	2mm 2-Pin Header	COMM CON	(626) 301-4200
JP4	1	2202S-05-G2	2mm Dual 5-Pin Header	COMM CON	(626) 301-4200
L1	1	ETQP6F1R2HFA	1.2µH Inductor	PANASONIC	(201) 348-7522
M1, M2, M3	3	FDS6680A	30V 0.013Ω N-Channel MOSFET	FAIRCHILD	(408) 822-2126
R1	1	CR10-104JM	100k 1/10W 5% Chip Resistor	TAD	(800) 508-1521
R2, R5, RS1	3	CR10-100FM	10Ω 1/10W, 1% Chip Resistor	TAD	(800) 508-1521
R6	1	CR10-685JM	680k 1/10W 5% Chip Resistor	TAD	(800) 508-1521
R8	1	CR10-0R0JM	0Ω 1/10W Chip Resistor	TAD	(800) 508-1521
RC1	1	CR10-333JM	33k 1/10W 5% Chip Resistor	TAD	(800) 508-1521
RCS1	1	LRF2010-01-R004F	0.004Ω 1/2W 1% Resistor	IRC	(361) 992-7900
RF1	1	CR10-470JM	4.7Ω 1/10W, 5% Chip Resistor	TAD	(714) 255-9123
U1	1	LTC1736CG	IC, LTC1736CG24	LTC	(408) 432-1900
	8	CCIJ2mm-138-G	JUMPER	COMM CON	(626) 301-4200



QUICK START GUIDE

This demonstration board is easy to set up to evaluate the performance of the LTC1736. Please follow the procedure outlined below for proper operation. Soldered wire connections are required to properly evaluate the performance of this switching regulator.

- Refer to Figure 2 for proper connection of monitoring and measurement equipment.
- Connect the input power supply to the V_{IN} and GND terminals on the right-hand side of the board with soldered connections. Do not increase V_{IN} over 28V or the MOSFET(s) WILL BE DAMAGED.
- Connect the load between the V_{OUT} and GND terminals on the right side of the board with soldered connections.
- The RUN pin can be left unconnected. To shut down the LTC1736, tie this pin to ground.

• Set jumper JP4 for the desired output voltage. (See

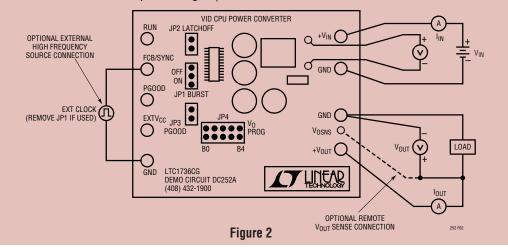
- If an external 5V supply is used, connect it to EXTV_{CC}.
- Set the jumper JP1 so that FCB selects the desired mode:

JP1	MODE
On	Burst Mode Operation, Connect PGood to FCB/Sync
Off	Forced Continuous
Open	Apply External Clock to FCB/Sync

 Jumper JP2 determines if the overcurrent latchoff is enabled. With JP2 installed this function is disabled. Remove JP2 to enable.

JP2	OVERCURRENT LATCHOFF
Installed	Disabled
Removed	Enabled

• Active loads can cause confusing results. Refer to the active load discussion in the Operation section.



INTRODUCTION

Table 1.)

The circuit in Figure 1 highlights the capabilities of the LTC1736.

The LTC1736 is a synchronous step-down switching regulator controller that drives external N-channel power MOSFETs using a fixed frequency architecture with OPTI-LOOP compensation. OPTI-LOOP compensation effectively removes the constraints placed on C_{OUT} by other controllers for proper operation (such as restrictions on very low ESRs). Burst Mode operation provides high efficiency at

low load currents. Operating efficiencies typically exceed 80% over more than two decades of load current range.

Do not use spring clip leads when testing this circuit. Soldered wire connections are required to properly test the performance of the PC board.

This demonstration circuit is intended for the evaluation of the LTC1736 switching regulator IC and was not designed for any other purpose.



4

The operating frequency is set by an external capacitor, C_{OSC1} , allowing maximum flexibility in optimizing efficiency. In this application, the frequency is set to 270kHz. A multifunction control pin, FCB, inhibits Burst Mode operation (reducing noise and RF interference), as well as allowing synchronization to an external oscillator.

Soft-start is provided by an external capacitor, C_{SS1} , which can be used to properly sequence supplies. The operating current level is user programmable via an external current sense resistor and is set to 11A. Short-circuit current is limited to approximately 4A by internal current foldback.

Measuring Voltage Regulation

When trying to measure voltage regulation, remember that all measurements must be taken at the point of regulation. This point is where the LTC1736's control loop looks for the information to keep the output voltage constant. In this demonstration board it is located between Pin 5 (SGND) of the LTC1736 and the sense side of $R_{\rm S1}$. This point corresponds to the $V_{\rm OSNS}$ terminal of the board. Output voltage test leads should be attached directly to this terminal. The load should be placed across the $V_{\rm OUT}$ (E7) and GND (E8) terminals. Measurements should not be taken at the end of test leads at the load; refer to Figure 2 for the proper monitoring equipment configuration.

This applies to line regulation (input to output voltage regulation) as well as load regulation tests. In doing line regulation tests, always look at the input voltage across the input terminals.

Remote Output Voltage Sensing

Remote output voltage sensing can be accomplished by connecting the V_{OSNS} terminal with another wire directly to the load. A 10Ω resistor, R_{S1} , connects V_{OUT} to V_{OSNS} to avoid open sense conditions. Never under any circumstance connect the load to V_{OSNS} !

Output Voltage Programming

The output voltage is digitally set to levels between 0.925V and 2.00V using the voltage identification (VID) inputs B0 to B4 set by jumper JP4. The internal 5-bit DAC configured

as a precision resistor voltage divider sets the output voltage in 50mV/25mV increments according to Table 1.

Table 1. VID Output Voltage Programming

	- abio ii ii bu					
B4	В3	B2	B1	В0	V _{OUT} (V)	
0	0	0	0	0	2.000V	
0	0	0	0	1	1.950V	
0	0	0	1	0	1.900V	
0	0	0	1	1	1.850V	
0	0	1	0	0	1.800V	
0	0	1	0	1	1.750V	
0	0	1	1	0	1.700V	
0	0	1	1	1	1.650V	
0	1	0	0	0	1.600V	
0	1	0	0	1	1.550V	
0	1	0	1	0	1.500V	
0	1	0	1	1	1.450V	
0	1	1	0	0	1.400V	
0	1	1	0	1	1.350V	
0	1	1	1	0	1.300V	
0	1	1	1	1	*	
1	0	0	0	0	1.275V	
1	0	0	0	1	1.250V	
1	0	0	1	0	1.225V	
1	0	0	1	1	1.200V	
1	0	1	0	0	1.175V	
1	0	1	0	1	1.150V	
1	0	1	1	0	1.125V	
1	0	1	1	1	1.100V	
1	1	0	0	0	1.075V	
1	1	0	0	1	1.050V	
1	1	0	1	0	1.025V	
1	1	0	1	1	1.000V	
1	1	1	0	0	0.975V	
1	1	1	0	1	0.950V	
1	1	1	1	0	0.925V	
1	1	1	1	1	**	
	+ + + D					

Note: *, ** Represents codes without a defined output voltage as specified in Intel specifications. The LTC1736 interprets these codes as a valid input and produces output voltage as follows: [01111] = 1.250V, [11111] = 0.900V.

DEMO MANUAL DC252 DESIGN-READY SWITCHER

OPERATION

The VID codes (00000-11110) are engineered to be compatible with Intel Mobile Pentium[®] II Processor specifications for output voltages from 0.925V to 2.00V.

The LSB (B0) represents 50mV increments in the upper voltage range (2.00V to 1.30V) and 25mV increments in the lower voltage range (1.275V to 0.925V). The MSB is B4. When all bits are low or grounded, the output voltage is 2.00V.

Each VID digital input is internally pulled up by a 40k resistor in series with a diode from VIDV $_{CC}$. Therefore, digital inputs must be grounded to get a digital low input, and digital inputs can be either left unconnected or connected to VIDV $_{CC}$ to get a digital high input. The series diode is used to prevent the digital inputs from being damaged or clamped if they are driven higher than VIDV $_{CC}$. The digital inputs accept CMOS voltage levels.

Maximum Input Voltage Considerations

The recommended maximum input voltage of this board is 24V for nominal output voltages. The minimum on-time for the LTC1736 is generally about 200ns and the operating frequency for this board is set to 270kHz. This imposes a limit on the maximum input voltage when programming low output voltages. For output voltages below 1.2V the maximum input voltage is limited to:

 $V_{IN(MAX)} < 20 (V_{OUT})$

If a higher operating input voltage is required with $V_{OUT} < 1.2V$, the operating frequency can be decreased by increasing C_{OSC1} . Refer to the LTC1736 data sheet for details. If the duty cycle falls below what can be accommodated by the minimum on-time, the LTC1736 will begin to skip cycles. The output voltage will continue to be regulated, but the ripple current and ripple voltage will increase.

Power-Good Output

A window comparator monitors the output voltage and its open-drain output (E1) is pulled low when the divided output voltage is not within $\pm 7.5\%$ of the reference voltage of 0.8V. Jumper JP3 connects pull-up resistor R1 from INTV_{CC} to the power-good output, E1. This jumper is provided to allow other pull-up voltages to be used. Make

sure the maximum voltage on PGOOD is less than 7V. During shutdown, the PGOOD output is pulled low.

INTV_{CC} Regulator

An internal, P-channel, low dropout regulator produces the 5.2V supply that powers the drivers and internal circuitry within the LTC1736. The INTV $_{\rm CC}$ pin can supply up to 50mA (this includes the gate-drive currents). External loading of the INTV $_{\rm CC}$ pin can be thermally limited (allow 10mA to 20mA for gate-drive currents). At high input voltages, the maximum junction temperature rating for the LTC1736 may be exceeded if too large an external load is placed on INTV $_{\rm CC}$. See the LTC1736 data sheet for details.

EXTV_{CC} Connection

The LTC1736 contains an internal P-channel MOSFET switch connected between the EXTV $_{CC}$ and INTV $_{CC}$ pins. The switch closes and supplies the INTV $_{CC}$ power whenever the EXTV $_{CC}$ pin is above 4.7V; it remains closed until EXTV $_{CC}$ drops below 4.5V. This allows the MOSFET driver and control power to be derived from the EXTV $_{CC}$ pin instead of V $_{IN}$. Do not apply greater than 7V to the EXTV $_{CC}$ pin and ensure that EXTV $_{CC}$ < V $_{IN}$. Additional efficiency gains can be realized by powering INTV $_{CC}$ from other high efficiency sources, such as a 5V system power supply.

The following list describes the most common possible connections for $\mathsf{EXTV}_\mathsf{CC}$ for low output voltage applications:

- 1. EXTV $_{CC}$ left open (or grounded); this will cause INTV $_{CC}$ to be powered from the internal 5.2V regulator resulting in an efficiency penalty at low load currents and high input voltages.
- 2. EXTV_{CC} connected to an external supply; if an external, high efficiency supply is available in the 5V to 7V range (EXTV_{CC} < V_{IN}), it may be used to power EXTV_{CC}, providing an efficiency boost. The typical connection in a notebook CPU power solution is to connect it to the main 5V system power supply.

Pentium is registered trademark of Intel Corportion.



Low Current Modes and Synchronization

The FCB input pin, set by jumper JP1 and FCB/Sync terminal E4, allows the selection of the low current operating mode and external frequency synchronization of the switching regulator.

Tying the FCB pin to ground with JP1 forces the controller into PWM or forced continuous mode. In forced continuous mode, the output MOSFETs are always driven, regardless of output loading conditions. Operating in this mode allows the switching regulator to source or sink current—but be careful; when the output stage sinks current, power is transferred back into the input supply terminals and the input voltage rises.

Burst Mode operation is enabled when the voltage applied to the FCB pin is greater than 0.8V (i.e., JP1 tied to INTV_{CC}) or if the pin is left open. A comparator with a precision 0.8V threshold allows the pin to be used to regulate a secondary winding on the switching regulator's output. A small amount of hysteresis is included in the design of the comparator to facilitate clean secondary operation. When the resistively divided secondary output voltage falls below the 0.8V threshold, the controller operates in the forced continuous operating mode for as long as it takes to bring the secondary voltage above the 0.8V + hysteresis level.

The internal LTC1736 oscillator can be synchronized to an external oscillator by clocking the FCB pin with a signal above 1.5V_{P-P} (Remember to remove jumper JP1). When the LTC1736 is synchronized to an external frequency, Burst Mode operation operation is disabled but cycle skipping is allowed at low load currents, since current reversal is inhibited. The bottom gate will come on every 10 clock cycles to ensure that the bootstrap capacitor C_{B1} is kept charged. The rising edge of an external clock applied to the FCB pin starts a new cycle.

When the LTC1736 is synchronized to an external clock, burst inhibit mode allows heavily discontinuous, low audio noise, constant frequency operation down to approximately 1% of maximum designed load current. This mode results in the elimination of switching frequency subharmonics over 99% of the output load range. Switching cycles start to be dropped at approximately 1% of

maximum designed load current in order to maintain proper output voltage.

The range of synchronization is from 240kHz to 350kHz with $C_{OSC} = 47 pF$. Attempting to synchronize to a higher frequency than 350kHz can result in inadequate slope compensation and cause loop instability with high duty cycles. If loop instability is observed while synchronized, additional slope compensation can be obtained by simply decreasing C_{OSC} .

The following table summarizes the possible states available on the FCB/Sync pin:

FCB/SYNC PIN	CONDITION
DC Voltage: 0V to 0.7V	Burst Disabled/Forced Continuous Current Reversal Enabled
DC Voltage: ≥ 0.9V	Burst Mode Operation, No Current Reversal
Feedback Resistors	Regulating a Secondary Winding
Ext Clock: (0V to V _{FCB/SYNC}) (V _{FCB/SYNC} > 1.5V)	Burst Mode Operation Disabled No Current Reversal

DC252 Modifications (MOSFETs)

The DC252 demo board has various modification provisions. Additional pad locations are available for adding extra output capacitors together with an extra footprint for a parallel topside MOSFET.

When operating at high input voltages, the transition losses of the topside MOSFET (M2) become very significant. Be sure to consider power loss due to transition losses as well as $R_{DS(ON)}$ losses. Don't over specify the topside MOSFET. (Refer to the LTC1736 data sheet for details.)

Refer to the LTC1736 data sheet for further information on the internal operation and functionality descriptions of the IC.

DC252 Modifications (Output Capacitors)

Four Matsushita SP output capacitors are installed on the demo board. Other output capacitors may freely be substituted provided they meet the load transient requirements. OPTI-LOOP compensation allows the transient response to be optiumized over a wide range of output capacitance and ESR values while minimizing output capacitance.



DEMO MANUAL DC252 DESIGN-READY SWITCHER

OPERATION

The output capacitors are generally determined by ESR (effective series resistance) and voltage rating rather than capacitance. The ESR must be small enough that output ripple voltage and any voltage droop due to high load current transients stay within the specifications of the CPU. The output capacitance must be large enough to hold up the output voltage until the inductor current has ramped up or down to its new value. With proper OPTI-LOOP compensation components, the response time is optimized and the output capacitance is minimized. The compensation components installed on the demo board are appropriate for the output capacitors specified in the parts list.

Additional mounting locations exist for through hole Sanyo OS-CON output capacitors, should they be desired. Combinations of different types of capacitors have proved to yield cost effective solutions. ESL (equivalent series inductance), typically not specified, can reduce the effectiveness of the ESR at high load current slew rates, so be careful in specifying the output capacitor.

Overcurrent Protection

The RUN/SS capacitor, C_{SS1} , is used initially to turn on and limit the inrush current of the controller. After the controller has been started and given adequate time to charge the output capacitor and provide full load current, C_{SS1} is used as a short-circuit time-out circuit. If the output voltage falls to less than 70% of its nominal value, CSS1 begins discharging on the assumption that the output is in an overcurrent and/or short-circuit condition. If the condition lasts for a long enough period, as determined by the size of C_{SS1}, the controller will be shut down until the RUN/SS pin voltage is recycled. This built-in latchoff can be overridden by providing >5µA pull-up at a compliance of 4V to the RUN/SS pin by installing jumper JP2. This current shortens the soft-start period but also prevents net discharge of the RUN/SS capacitor during an overcurrent and/or short-circuit condition.

Foldback current limiting is activated when the output voltage falls below 70% of its nominal level, whether or not the short-circuit latchoff circuit is enabled.

With the overcurrent latchoff enabled, a slow ramp on the input voltage may cause the circuit to latch off. Simply re-

cycle the run pin to start. Refer to the LTC1736 data sheet for details.

Overvoltage Protection

The output is protected from overvoltage by a "soft-latch." When the output voltage exceeds the regulation value by more than 7.5%, the synchronous MOSFET turns on, and remains on for as long as the overvoltage condition is present. If the output voltage returns to a safe level, normal operation resumes. This self-resetting action prevents "nuisance trips" due to momentary transients and eliminates the need for the Schottky diode that is necessary with conventional OVP to prevent V_{OLIT} reversal.

Because of the inherent self-resetting action of the soft-latch, dynamic changing of the VID control bits does not latch off the LTC1736. When a new output voltage is set via the VID bits, the control loop simply adjusts the output voltage and the overvoltage protection threshold to this new level without causing a fault.

The overvoltage threshold tracks the new output voltage. protecting the load at all times. Figure 3a and Figure 3b both show an example of a dynamic VID code change resulting in a programmed output voltage change from 1.5V to 1.3V at a constant 5 ampere load current. At the instant the VID code is changed, the control loop begins to respond to the new output voltage, and the power-good output is asserted low since the new programmed output voltage is outside the 7.5% window. When the new output voltage is within 7.5% of its new programmed value, the power-good signal goes high. Figure 3a shows a VID code change with the FCB pin low (Burst Mode operation disabled). Figure 3b shows a dynamic VID code change with Burst Mode operation active. If dynamic VID changes are required and Burst Mode operation is desired, connect the PGOOD output (E1) to the FCB/Sync input (E4) and remove jumper JP1. This connection automatically forces continuous operation whenever the power-good output is low, providing fast response to VID changes regardless of load current.

Active Loads— Beware

Beware of active loads! They are convenient but problematic. Some active loads do not turn on until the applied



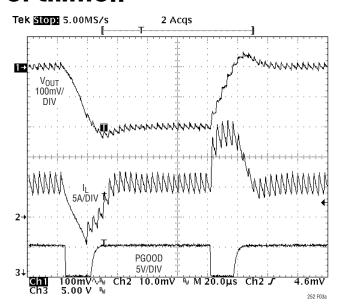


Figure 3a. Dynamic VID Change, Burst Mode Operation Defeated

voltage rises above 0.1V to 0.8V. The turn-on may be delayed as well. A switching regulator with soft-start may appear to start up, then shut down and, eventually, reach the correct output voltage. What happens is as follows: at switching regulator turn-on, the output voltage is below the active load's turn-on requirements. The switching regulator's output rises to the correct output voltage level due to the inherent delay in the active load. The active load turns on after its internal delay and then pulls down the switching regulator's output because the switcher is in its soft-start interval. The switching regulator's output may come up at some later time when the soft-start interval has passed.

A switching regulator with foldback current limit will also have difficulty with the unrealistic I-V characteristic of the active load. Foldback current limiting will reduce the output current available as the output voltage drops below a threshold level (this level is 70% of nominal V_{OUT} for the LTC1736). This reduction in available output current will result in the active load immediately pulling down the output because the active load's current demand remains constant as the output voltage decreases. Most actual loads do not behave like the active load I-V characteristics. Actual loads normally have a $V_{IN} \cdot C \cdot f$ dependency, where C is internal chip capacitance and f is the frequency of operation. To alleviate the active-load problem during

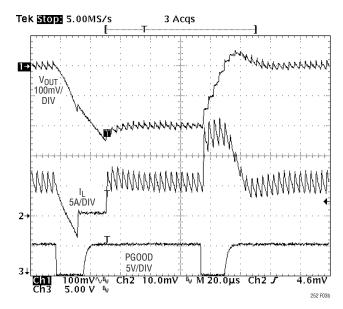


Figure 3b. Dynamic VID Change, Burst Mode Operation Enabled

testing, the active load should be initially programmed to a much lower current value until the switching regulator's soft-start interval has passed and then increased to the higher level. The switching regulator will supply the increased current required according to the transient response of the switching regulator. Output capacitance needs to be sufficient to accommodate the current step during the transient period, keeping the output voltage at or above the foldback threshold of 70%.

Checking Transient Response

OPTI-LOOP compensation effectively removes the constraints placed on C_{OUT} by other controllers (such as restrictions on very low ESRs). The output capacitors used in this demo board have very low ESRs; other types may be substituted but be carefull to measure the load step transient response and verify the specfications on output voltage continue to be met during transients.

A partial list of low ESR capacitors that are suitable for this application is included in the parts list. Each has its own cost, size, ESL and other performance trade offs. Combinations of capacitors have been shown to work well, too, so feel free to experiment. An example of a combination that works well is an OS-CON, $820\mu F/4V$ capacitor in parallel with a $180\mu F/4V$ Matsushita SP series capacitor. The SP capacitor tames the ESL-induced characteristic of



the otherwise low ESR OS-CON. The I_{TH} OPTI-LOOP compensation components shown in Figure 1's circuit will provide an adequate starting point for most applications.

The load-step response with the output voltage set to 1.6V is shown in Figures 4a and 4b using four $180\mu F/4V$ Matsushita SP series for the output capacitors. Figure 4a is a 0A to 12A load step with Burst Mode operation inhibited (FCB = 0V). Figure 4b shows the load step response for a 10mA to 12A load current transition with Burst Mode operation enabled (FCB = 5V).

The regulator loop response can be checked by looking at the load current transient response. Switching regulators take several cycles to respond to a step in DC (resistive) load current. When a load step occurs, V_{OUT} shifts by an amount equal to ΔI_{LOAD} (ESR), where ESR is the effective series resistance of C_{OUT} . ΔI_{LOAD} also begins to charge or discharge C_{OUT} , generating the feedback error signal that forces the regulator to adapt to the current change and return V_{OUT} to its steady-state value. During this recovery time, V_{OUT} can be monitored for excessive overshoot or ringing, which would indicate a stability problem. OPTI-

LOOP compensation allows the transient response to be optimized over a wide range of output capacitances and ESR values. The availability of the I_{TH} pin not only allows optimization of control loop behavior but also provides a DC coupled and AC filtered closed-loop-response test point. The DC step, rise time and settling at this test point truly reflect the closed-loop response. Assuming a predominantly first order system, phase margin and/or damping factor can be estimated using the percentage of overshoot seen at this pin. The bandwidth can also be estimated by examining the rise time at the pin.

The I_{TH} series R_{C1} – C_{C2} , C_{C1} filter sets the dominant polezero loop compensation. The values can be modified slightly (from 0.5 to 2 times their suggested values) to optimize transient response once the final PC layout is done and the particular output capacitor type and value have been determined. The output capacitors need to be decided upon because the various types and values determine the loop feedback factor gain and phase. An output current pulse of 20% to 100% of full load current having a rise time of 1 μ s to 10 μ s will produce output voltage and

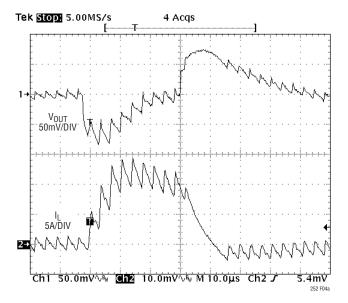


Figure 4a. Load Step Response with Burst Mode Operation Disabled

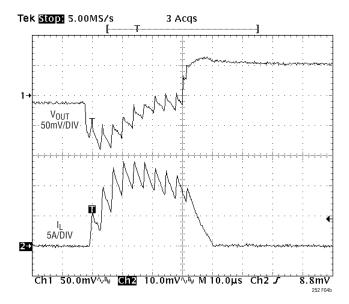
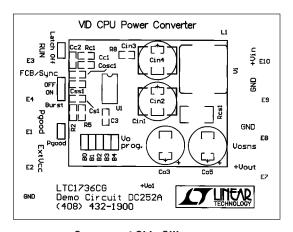


Figure 4b. Load Step Response with Burst Mode Operation Enabled

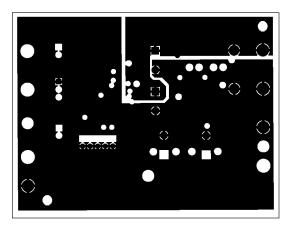
 I_{TH} pin waveforms that will give a sense of the overall loop stability without breaking the feedback loop. The AC gain of the loop will be increased by increasing R_{C1} and the bandwidth of the loop will be increased by decreasing C_{C2} . If R_{C1} is increased by the same factor that C_{C2} is decreased, the zero frequency will be kept the same, thereby keeping the phase the same in the most critical frequency range of the feedback loop. The output voltage settling

behavior is related to the stability of the closed-loop system and will demonstrate the actual overall supply performance. Capacitor C_{C2} provides some high frequency decoupling against transients. Be carefull not to overspecify its value, as the response time to a load step will be degraded. Again, monitoring the I_{TH} pin will show any slew rate limitations due to C_{C1} . For further explanation of optimizing loop response, refer to Application Note 76.

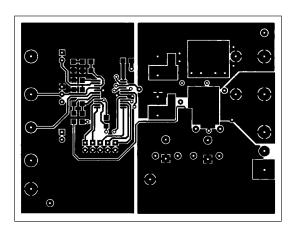
PCB LAYOUT AND FILM



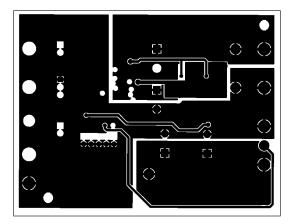
Component Side Silkscreen



Internal Copper (Layer 2)



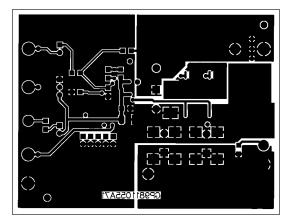
Component Side Copper (Layer 1)



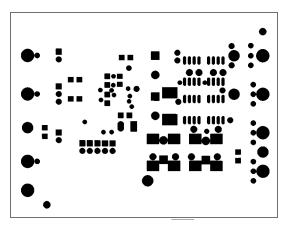
Internal Copper (Layer 3)



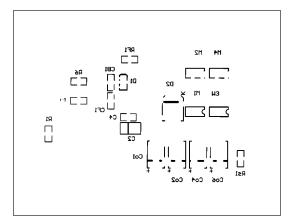
PCB LAYOUT AND FILM



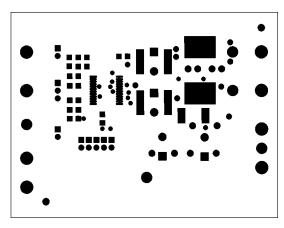
Bottom Side Copper (Layer 4)



Bottom Side Paste Mask

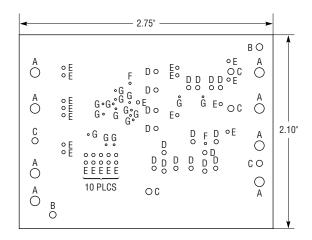


Bottom Side Silkscreen



Component Paste Mask

PC FAB DRAWING



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ALL DIMENSIONS ARE IN INCHES, ±0.003. FINISHED HOLE SIZES ARE +0.003/-0.
 2. FINISHED MATERIAL IS FR4, 0.062 THICK, 1 OZ Cu, 4 LAYERS.
 PLATED HOLE WALL THICKNESS 0.001 MIN. INTERNAL LAYERS 1 OZ Cu.

- 3. PROCESS AND PLATING: SMOBC
- 4. SOLDERMASK BOTH SIDES USING GLOSSY GREEN LPI.
- 5. SILKSCREEN WHITE NONCONDUCTIVE INK BOTH SIDES.

SYMBOL	DIAMETER	NUMBER OF HOLES	PLATED
Α	0.100	8	YES
В	0.070	2	NO
С	0.065	5	YES
D	0.045	18	YES
Е	0.035	25	YES
F	0.025	2	YES
G	0.020	15	YES

252 PC Fab Dwg

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Power Management IC Development Tools category:

Click to view products by Analog Devices manufacturer:

Other Similar products are found below:

EVAL-ADM1168LQEBZ EVB-EP5348UI MIC23451-AAAYFL EV MIC5281YMME EV DA9063-EVAL ADP122-3.3-EVALZ ADP1300.8-EVALZ ADP130-1.2-EVALZ ADP130-1.5-EVALZ ADP130-1.8-EVALZ ADP1714-3.3-EVALZ ADP1716-2.5-EVALZ ADP1740-1.5EVALZ ADP1752-1.5-EVALZ ADP1828LC-EVALZ ADP1870-0.3-EVALZ ADP1871-0.6-EVALZ ADP1873-0.6-EVALZ ADP1874-0.3EVALZ ADP1882-1.0-EVALZ ADP199CB-EVALZ ADP2102-1.25-EVALZ ADP2102-1.875EVALZ ADP2102-1.8-EVALZ ADP2102-2EVALZ ADP2102-3-EVALZ ADP2102-4-EVALZ ADP2106-1.8-EVALZ ADP2147CB-110EVALZ AS3606-DB BQ24010EVM
BQ24075TEVM BQ24155EVM BQ24157EVM-697 BQ24160EVM-742 BQ24296MEVM-655 BQ25010EVM BQ3055EVM

NCV891330PD50GEVB ISLUSBI2CKIT1Z LM2744EVAL LM2854EVAL LM3658SD-AEV/NOPB LM3658SDEV/NOPB LM3691TL1.8EV/NOPB LM4510SDEV/NOPB LM5033SD-EVAL LP38512TS-1.8EV EVAL-ADM1186-1MBZ EVAL-ADM1186-2MBZ